

In the Claims

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims

1. (currently amended) A process for removing a thermal barrier ceramic coating from a cooling hole of a component comprising:  
  
drilling cooling holes into the component after a bond coat application and prior to a thermal barrier ceramic coating application;  
  
~~coating the component containing the cooling holes with the thermal barrier ceramic coating;~~  
  
directing an air jet at a side of the component, opposing a surface having the thermal barrier ceramic coating, the jet containing a non-abrasive spherical particulate media and emitting the media from a nozzle of the jet at a low pressure wherein said low pressure is insufficient for the media to damage a substrate but said low pressure is sufficient for the media to remove the thermal barrier ceramic coating from the cooling hole; and  
  
wherein a bond coating is interposed between the thermal barrier ceramic coating and the substrate; and  
  
wherein the pressure of the air jet is from about 20 to 100 PSIG.
2. (canceled)
3. (canceled)
4. (currently amended) The process of claim 1 wherein the spherical media particles have a diameter of from about 0.002 to 0.010 inches.
5. (previously presented) The process of claim 4 wherein the media is glass beads.